

**IN THE ABSTRACT OF THE DISCLOSURE:**

**Please delete the present Abstract of the Disclosure and replace it with the following new**

**Abstract of the Disclosure:**

A camera module including a light-transmissible board having an infrared rays cutting function on one surface of which a wiring pattern is formed, an image pickup element having a photodetecting portion which is flip-chip-mounted on the same surface of the light-transmissible board while the photodetecting portion is opposite to an area where there is no wiring-pattern, and a lens unit which is mounted on the other surface of the light-transmissible board so as to be located above the photodetecting portion of the image pickup element.

*Q20*